

**CLAIM AMENDMENT:**

Please amend claim 4, cancel claims 1-3 and add new claims 5 -7.

Claims 1-3 (canceled)

Claim 4 (currently amended): A lead frame for the semiconductor device from which surplus resin can be detached without leaving burrs, comprising  
a first region in which a semiconductor chip can be encapsulated with resin;  
and  
a second region in which an opening is formed, the opening having one end, which extends to the first region, and another opposite end opposite to the one end being rounded.

Claim 5 (new): A lead frame as claimed in claim 4 wherein the opening includes a first part and a second part, the first part being rectangularly shaped and the second part being semicircularly shaped.

Claim 6 (new): A lead frame as claimed in claim 5 wherein the sides facing to each other of the first part are parallel to sides of the lead frame.

Claim 7 (new): A lead frame as claimed in claim 4 wherein the first part is used for passing resin material, and the second part is used for storing resin material.